



Material Content Data Sheet



Sales Product Name		TLE42994GM		Issued		24. January 2018		
MA#		MA001396134						
Package		PG-DSO-14-30		Weight*		143.13 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.995	2.09	2.09	20927	20927
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		105	
	non noble metal	zinc	7440-66-6	0.060	0.04		422	
	non noble metal	iron	7439-89-6	1.207	0.84		8432	
wire	non noble metal	copper	7440-50-8	49.007	34.24	35.13	342385	351344
	noble metal	gold	7440-57-5	0.192	0.13	0.13	1340	1340
	encapsulation	organic material	carbon black	1333-86-4	0.172	0.12		1201
plastics	plastics	epoxy resin	-	7.910	5.53		55265	
	inorganic material	silicondioxide	60676-86-0	77.899	54.43	60.08	544234	600700
leadfinish	non noble metal	tin	7440-31-5	1.226	0.86	0.86	8566	8566
plating	noble metal	silver	7440-22-4	1.030	0.72	0.72	7195	7195
glue	plastics	acrylic resin	-	0.313	0.22		2184	
	noble metal	silver	7440-22-4	1.108	0.77	0.99	7744	9928
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com